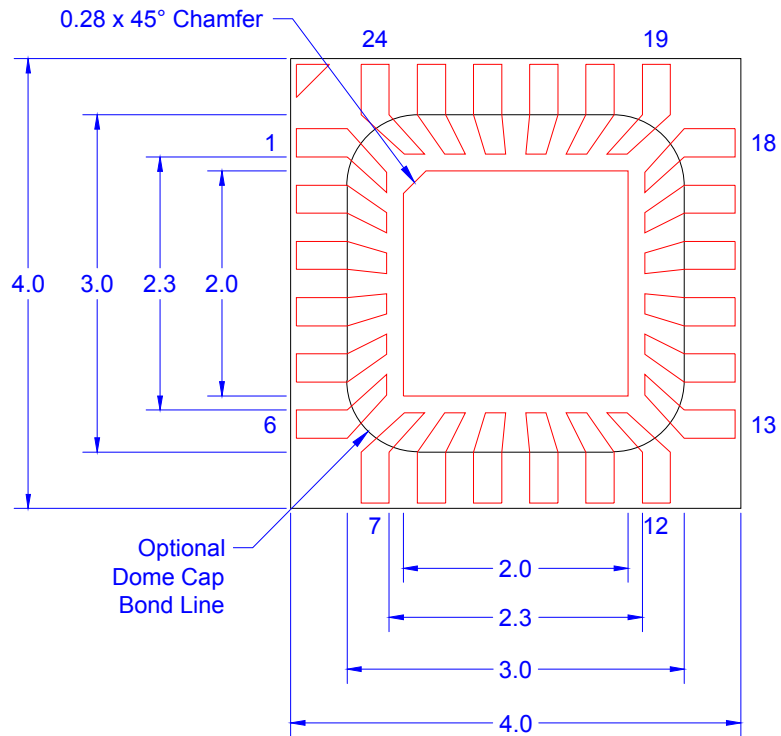
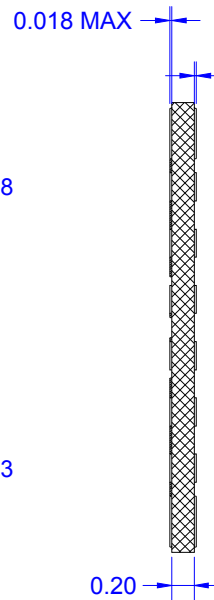


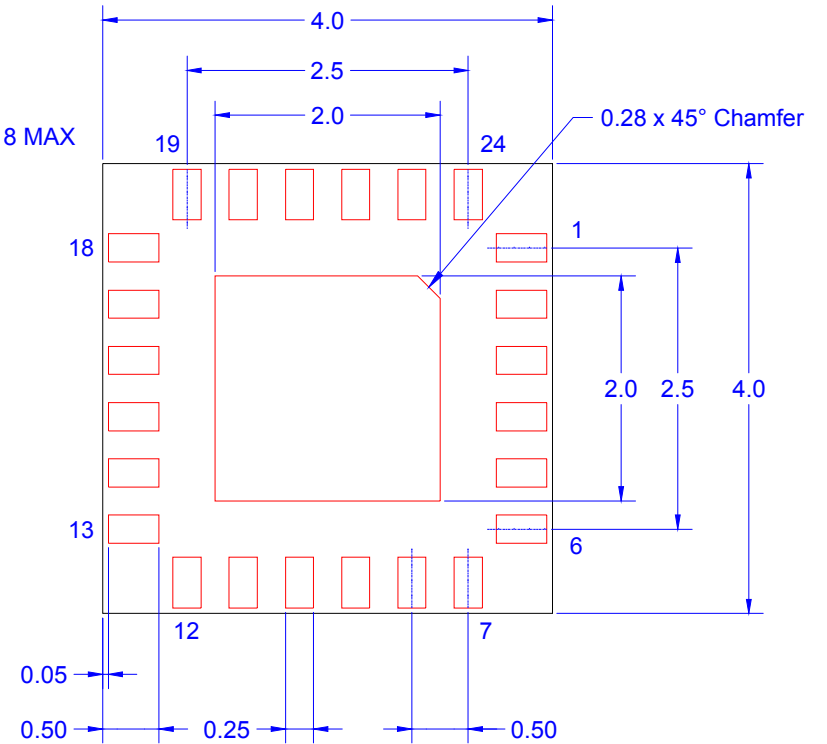
TOP VIEW



SIDE VIEW



BOTTOM VIEW



SIDE VIEW



NOTES:


1. Organic substrate.
2. Cavity without walls.
3. Pads: 1/2-oz Cu plating (See Plating Thickness Table).
4. Copper Thickness: 12µm~18µm (0.5~0.7mil).
5. Dimensions in MM (Unless otherwise stated).

SUBSTRATE TABLE

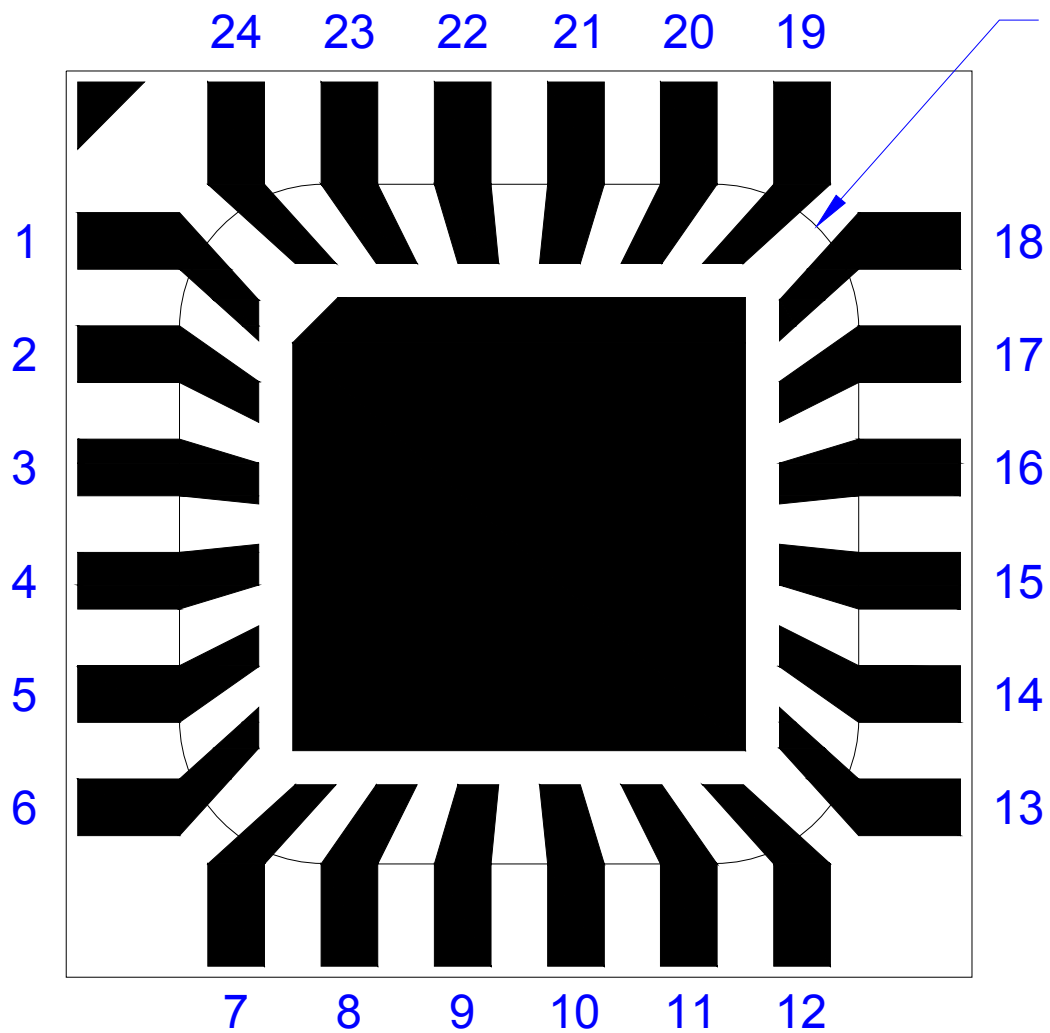
DWG	MAT'L	Dk	Df
452412	BT	4.4 @1GHz	.006 @1GHz
452442	RO4003C	3.55 @10GHz	.0027 @10GHz

PLATING THICKNESS TABLE


CODE	Type	Ni	Pd	Au - Top	Au - Bottom
G1	NiAu	3.8µm (150 micro-inch)	-	1.3µm (50 micro-inch)	0.13µm (5 micro-inch)
G2	NiPdAu	3.8µm (150 micro-inch)	1.3µm (50 micro-inch)	0.13µm (5 micro-inch)	0.13µm (5 micro-inch)

APPROVALS	DATE				
DRAWN T.Au	03/20/13				
ENG M. Hart	03/20/13	TITLE 24-LEAD 4MM P=0.50MM S-QFN (AIR) OPEN CAVITY			
MFG		SCALE NONE	SIZE A	DRAWING NO. 452412	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 2
CUST					
REVISED					

BONDING DIAGRAM



Optional
Dome Cap
Bond Line

APPROVALS		DATE				
DRAWN	T. Au	03/20/13				
ENG	M. Hart	03/20/13	TITLE 24-LEAD 4MM P=0.50MM S-QFN OPEN CAVITY			
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			NONE	A	452412 MKT	A
CUST			DO NOT SCALE DRAWING			SHEET 2 OF 2
REVISED						